

CONFIDENTIAL

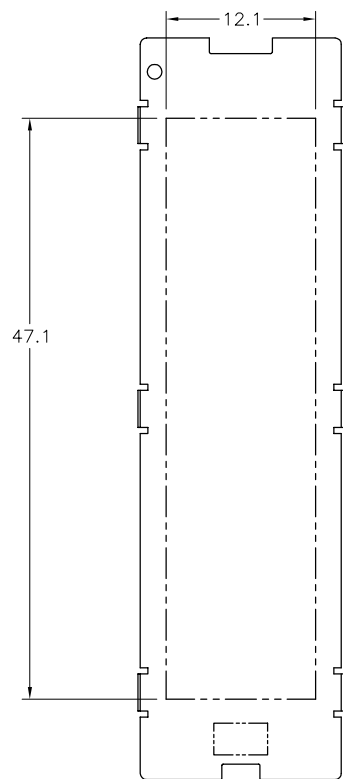
mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection MM	product family MEG-ARRAY
ltr	ec'n no	dr	date	tolerances unless otherwise specified		MM	title 6mm RECPT. ASSY. 12 X 44 = 528 POS.
A	V03-1102	LP	10/20/03	angles	X*3		
B	V04-0940	VS	10/13/04	parallelism	XX*13	scale 1:1	dwg no 10026846
C	V06-0560	LP	2006/07/14	flatness	XXX*051		
				dr	D.INGRAM	04/01/03	sheet 1 of 3 size A4
				enr	D.WHITING	04/01/03	
				chr	D.WHITING	04/01/03	
				appd	D.WHITING	04/01/03	
sheet index	revision sheet	C	C	C			type CUSTOMER Drawing
		1	2	3			



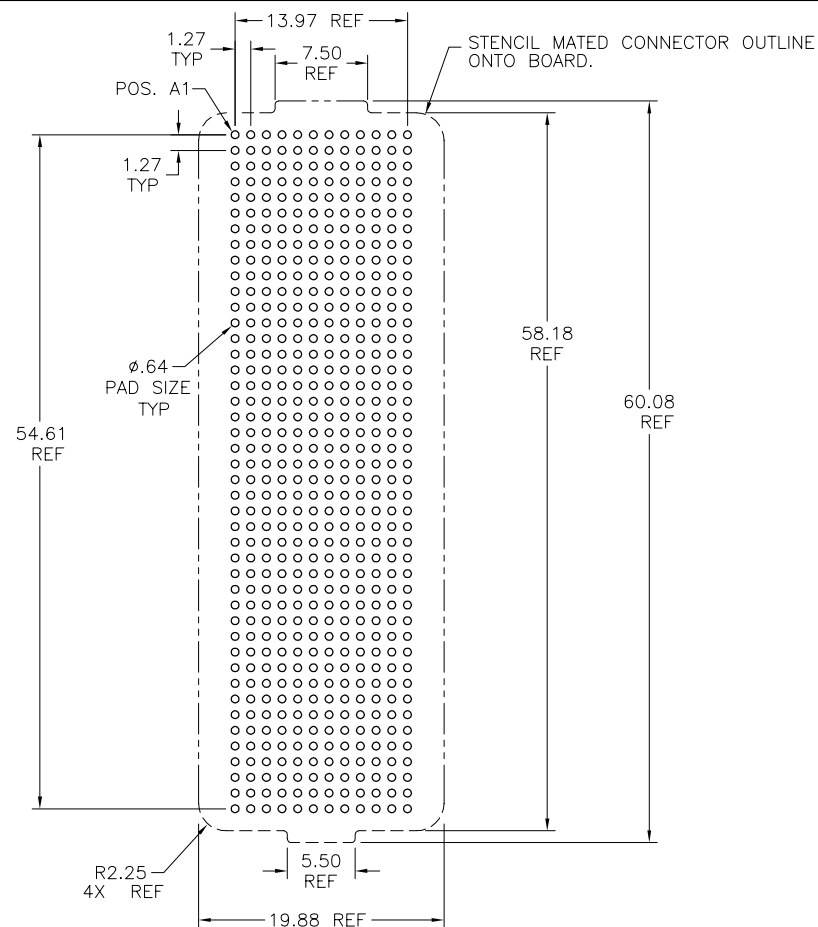
1 | 2

3

4



FLAT AREA FOR PICK UP CAP



BOARD PATTERN

A

A

B

B

1

2

3

4

mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection ⊕	product family MEG-ARRAY
ltr	ec'n no	dr	date	title 6mm RECT. ASSY. 12 X 44 = 528 POS.	
c			angles	MM	
			0° ±2'	scale 1:1	
		dr	D.INGRAM	04/01/03	FCI
		enr	D.WHITING	04/01/03	dwg no
		chr	D.WHITING	04/01/03	sheet 2 of 3
		appd	D.WHITING	04/01/03	size 10026846 A4
sheet index	revision sheet				type CUSTOMER Drawing

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	CONTACT PLATING
10026846-001	YES	15u" (.38u") Au OVER Ni	SnPb
10026846-001LF			SnAgCu LEAD FREE (5)(6)
10026846-101	YES	30u" (.76u") Au OVER Ni	SnPb
10026846-101LF			SnAgCu LEAD FREE (5)(6)
10026846-201	YES	SEE NOTE 4.	SnPb
10026846-201LF			SnAgCu LEAD FREE (5)(6)

NOTES:

①. **MAT'L:**

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEET3)
 SOLDER BALL: (SEE TABLE ON SHEET3)
 EUTECTIC SnPb OR LEAD FREE
 95.5Sn/4Ag/0.5Cu

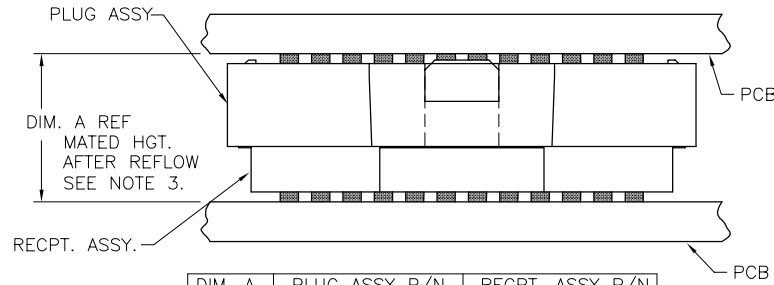
②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

④. PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.

⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



DIM. A	PLUG ASSY P/N	RECPT. ASSY P/N
6.0	10022671-X02	10026846-X01

MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

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c				angles	XXX*13	scale 1:1		dwg no 10026846	
				0° ±2'	XXX*051	FCI		sheet 3 of 3 size A4	
		dr	D.INGRAM	04/01/03				type CUSTOMER Drawing	
		enr	D.WHITING	04/01/03					
		chr	D.WHITING	04/01/03					
		appd	D.WHITING	04/01/03					
sheet index	revision sheet								